

In the claims:

For the Examiner's convenience, all pending claims are presented below.

1. (Previously Presented) An apparatus comprising:
a printed circuit board (PCB);
a connector mounted on the PCB; and
an integrated circuit (IC) package for insertion into the connector, the IC package
having a plurality of input/output (I/O) lands with a varied pitch distance.
2. (Original) The apparatus of claim 1 wherein the plurality of lands include a
vertical pitch having a first distance and a horizontal pitch having a second distance.
3. (Original) The apparatus of claim 1 wherein the connector includes a plurality
of contacts having a varied pitch distance to match the plurality of lands.
4. (Original) The apparatus of claim 3 wherein the PCB comprises a plurality of
land pads having a varied pitch distance to match the plurality of contacts.
5. (Original) The apparatus of claim 4 wherein the PCB comprises a plurality of
traces coupled to the plurality of land pads.
6. (Original) The apparatus of claim 1 wherein the PCB is a motherboard.
7. (Original) The apparatus of claim 1 wherein the connector is a zero insertion
force (ZIF) connector.
8. (Original) The apparatus of claim 1 wherein the IC package is a land grid
array (LGA).
9. (Previously Presented) An apparatus comprising:

a printed circuit board (PCB);
a connector mounted on the PCB; and
an integrated circuit (IC) package for insertion into the connector, the IC package having a plurality of input/output (I/O) pins with a varied pitch distance.

10. (Original) The apparatus of claim 9 wherein the plurality of pins include a vertical pitch having a first distance and a horizontal pitch having a second distance.

11. (Original) The apparatus of claim 10 wherein the PCB comprises a plurality of pin pads having a varied pitch distance to match the plurality of pins.

12. (Original) The apparatus of claim 9 wherein the IC package is a pin grid array (PGA).

13. (Previously Presented) An integrated circuit (IC) comprising:
a plurality of input/output pins (I/O) connectors having a varied pitch distance.

14. (Original) The IC of claim 13 wherein the plurality of I/O connectors include a vertical pitch having a first distance and a horizontal pitch having a second distance.

15. (Original) The IC of claim 13 wherein the plurality of I/O connectors comprise lands.

16. (Original) The IC of claim 13 wherein the plurality of I/O connectors comprise pins.